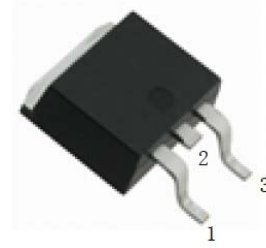
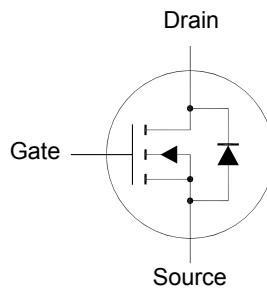


SFTN3910R

N-Channel Enhancement Mode MOSFET



1. Gate 2. Drain 3. Source
TO-252 Plastic Package

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current	I_D	$T_C = 25^\circ\text{C}$ 45 $T_C = 100^\circ\text{C}$ 28	A
Peak Drain Current ¹⁾	I_{DM}	180	A
Avalanche energy, single pulse ²⁾	E_{AS}	13	mJ
Avalanche current, single pulse ²⁾	I_{AS}	16	A
Power Dissipation	P_D	$T_C = 25^\circ\text{C}$ 33	W
Operating Junction Temperature Range	T_J	- 55 to 150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3.8	$^\circ\text{C}/\text{W}$

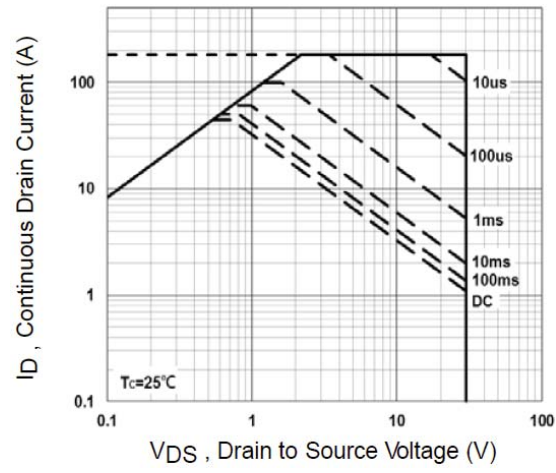
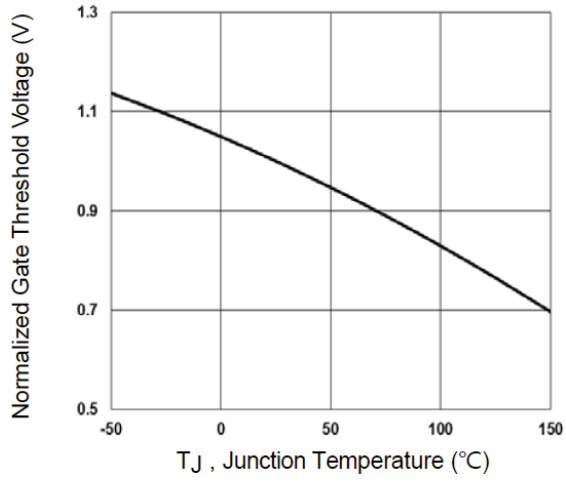
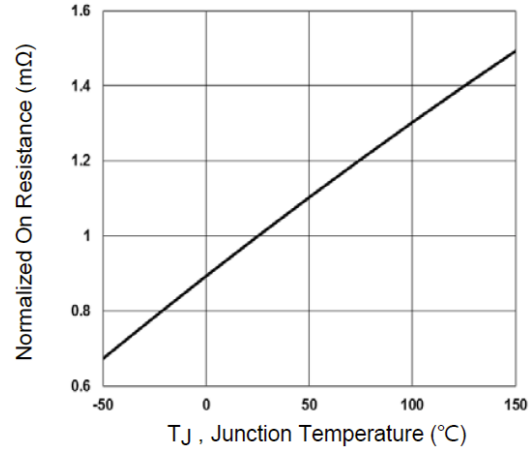
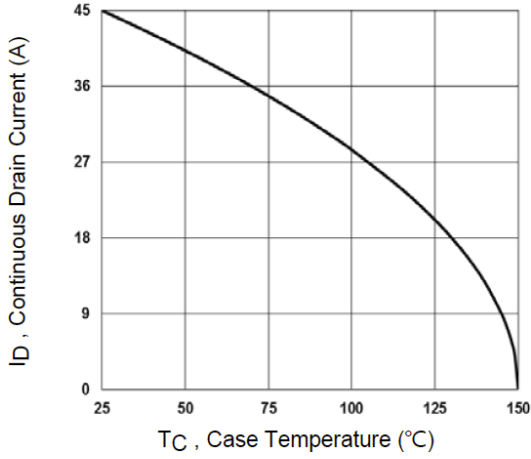
¹⁾ Repetitive Rating : Pulsed width limited by maximum junction temperature.

²⁾ $V_{DD}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=16\text{A}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.

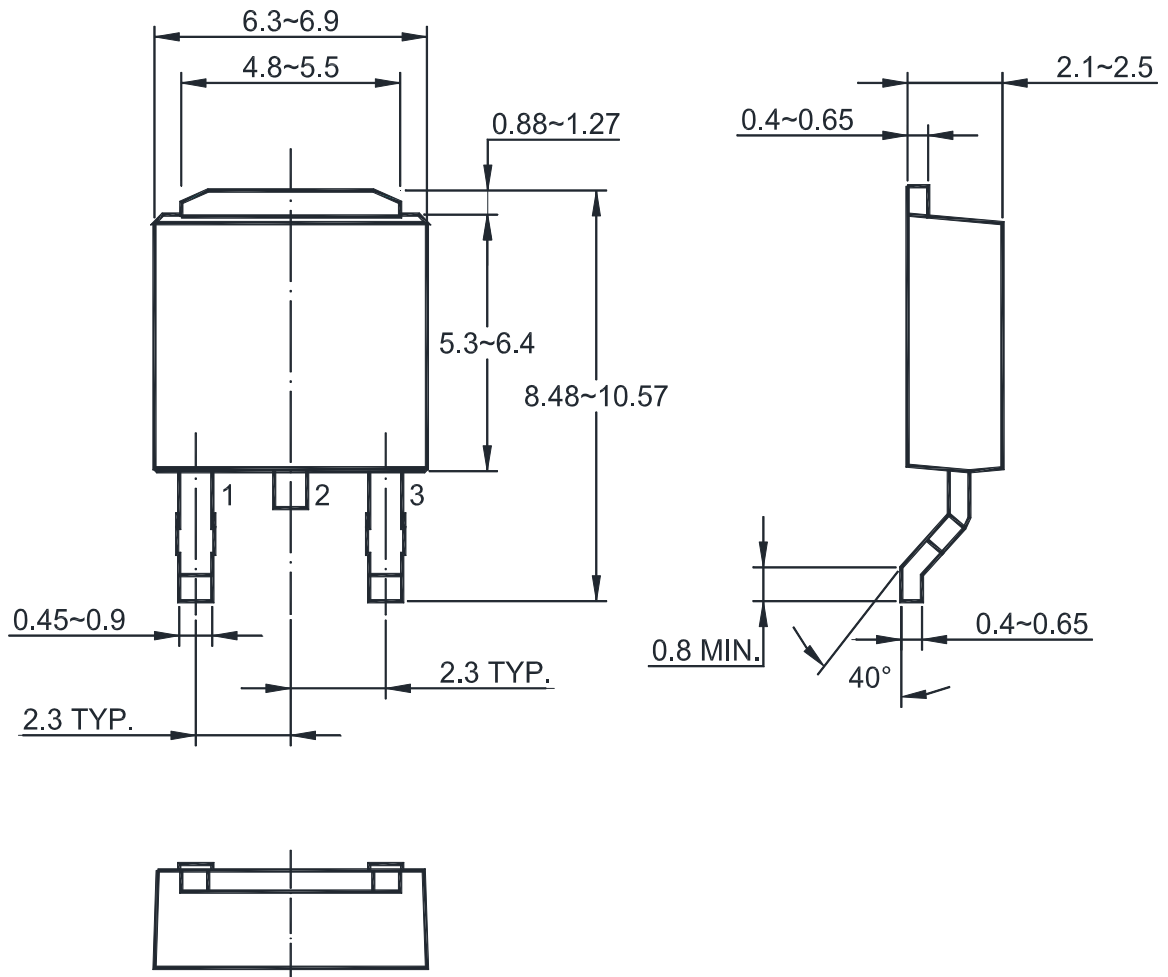
SFTN3910R

Characteristics at $T_J = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage at $I_D = 250 \mu\text{A}$	BV_{DSS}	30	-	-	V
Gate-Source Threshold Voltage at $V_{GS} = V_{DS}$, $I_D = 250 \mu\text{A}$	$V_{GS(th)}$	1.2	-	2.5	V
Drain-Source Leakage Current at $V_{DS} = 30 \text{ V}$ at $V_{DS} = 30 \text{ V}$, $T_J = 125^\circ\text{C}$	I_{DSS}	- -	- -	1 10	μA
Gate Leakage Current at $V_{GS} = \pm 20 \text{ V}$	I_{GSS}	-	-	± 100	nA
Drain-Source On-State Resistance at $V_{GS} = 10 \text{ V}$, $I_D = 10 \text{ A}$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 5 \text{ A}$	$R_{DS(on)}$	-	-	12 18	m Ω
Forward Transconductance at $V_{DS} = 10 \text{ V}$, $I_D = 3 \text{ A}$	$ g_{FS} $	-	6.4	-	S
Diode Forward Voltage at $I_S = 1 \text{ A}$	V_{SD}	-	-	1	V
Input Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{iss}	-	-	900	pF
Output Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{oss}	-	-	125	pF
Reverse Transfer Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{rss}	-	-	90	pF
Turn-On Delay Time at $V_{GS} = 10 \text{ V}$, $V_{DD} = 15 \text{ V}$, $I_D = 1 \text{ A}$, $R_G = 6 \Omega$	$t_{d(on)}$	-	-	7	ns
Turn-On Rise Time at $V_{GS} = 10 \text{ V}$, $V_{DD} = 15 \text{ V}$, $I_D = 1 \text{ A}$, $R_G = 6 \Omega$	t_r	-	-	19	ns
Turn-Off Delay Time at $V_{GS} = 10 \text{ V}$, $V_{DD} = 15 \text{ V}$, $I_D = 1 \text{ A}$, $R_G = 6 \Omega$	$t_{d(off)}$	-	-	42	ns
Turn-Off Fall Time at $V_{GS} = 10 \text{ V}$, $V_{DD} = 15 \text{ V}$, $I_D = 1 \text{ A}$, $R_G = 6 \Omega$	t_f	-	-	13	ns



TO-252 PACKAGE OUTLINE



Recommended Soldering Footprint

